

**INDUSTRY STANDARD OF THE
PEOPLE'S REPUBLIC OF CHINA**

SJ/T 2709-2016

Replacing SJ 2709-1986

**Methods of measurement for temperature of printed board
assemblies**

印制板组装件温度测试方法

(English Translation)

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What this standard covers

This standard specifies the test equipment, test conditions, test procedures and test data processing for the temperature test of printed board assemblies. This standard is applicable to testing the ambient temperature, temperature field, and component surface temperature of printed board assemblies.

Document data

Chinese classification (CCS): L30.

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